

8/21/02

) Docket Number: 96-0841.01

) Paper No.: 10

) Art Unit: 2815

Examiner: Brock II, P.

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**Certificate of Mailing (37 C.F.R. §1.8)**

20231, on the date below:

7/29/02 Tara Suelton

Date Signature

REPLY AND AMENDMENT UNDER 37 CFR §1.116

In the Claims:

25. (Twice Amended) A process for forming device isolation for a semiconductor assembly, said process comprising the steps of:

forming a first trench into a semiconductor substrate;